





40V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)} max	I _D max T _A = 25°C
-40V	80mΩ @ V _{GS} = -10V	-3.7 A
-40V	150m Ω @ V_{GS}= -4.5V	-2.8 A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor control
- **DC-DC** Converters
- Power management functions
- Uninterrupted power supply

Features and Benefits

- Fast switching speed
- Low gate drive
- Low input capacitance
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

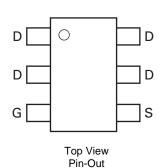
Mechanical Data

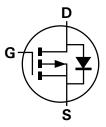
- Case: SOT26 •
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Weight 0.018 grams (approximate)



SOT26

Top View





Equivalent Circuit

Ordering Information (Note 3)

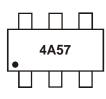
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMP4A57E6TA	4A57	7	8	3,000

Notes: 1. No purposefully added lead

2. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com.

3. For packaging details, go to our website at http://www.diodes.com.

Marking Information



4A57 = Product Type Marking Code



Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic		Symbol	Value	Unit	
Drain-Source voltage		V _{DSS}	-40	V	
Gate-Source voltage		V _{GS}	±20	V	
		(Note 5)		-3.7	
Continuous Drain current	$V_{GS} = 10V$	$T_{A} = 70^{\circ}C$ (Note 5)	I _D	-2.9	A
		(Note 4)		-2.9	
Pulsed Drain current	$V_{GS} = 10V$	(Note 6)	I _{DM}	-18	А
Continuous Source current (Body diode)	(Note 5)	I _S	-2.6	А
Pulsed Source current (Body diode) (Note 6)		I _{SM}	-18	А	

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit	
Power dissipation	(Note 4)	5	1.1 8.8		
Linear derating factor	(Note 5)	PD	1.7 13.7	mW/°C	
Thermal Resistance, Junction to Ambient	(Note 4)	D	113	°C/W	
mermai Resistance, Junction to Ambient	(Note 5)	R _{θJA}	73	-C/W	
Operating and storage temperature range		TJ, T _{STG}	-55 to 150	°C	

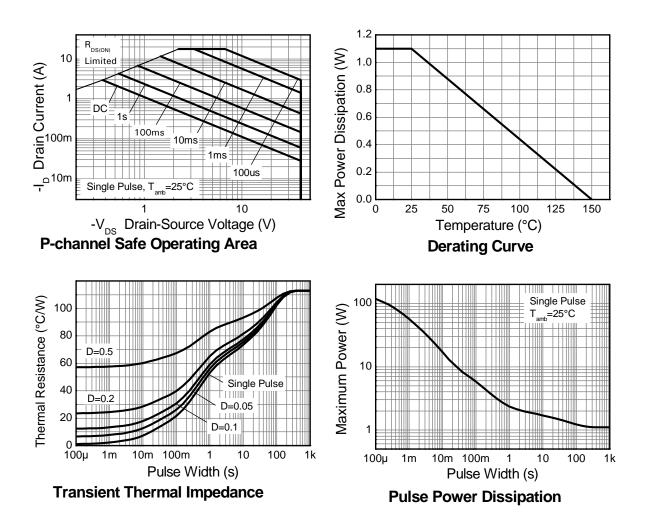
Notes: 4. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

5. Same as note (4), except the device is measured at t \leq 5 sec.

6. Same as note (4), except the device is pulsed with D = 0.02 and pulse width 300µs. The pulse current is limited by the maximum junction temperature.



Thermal Characteristics





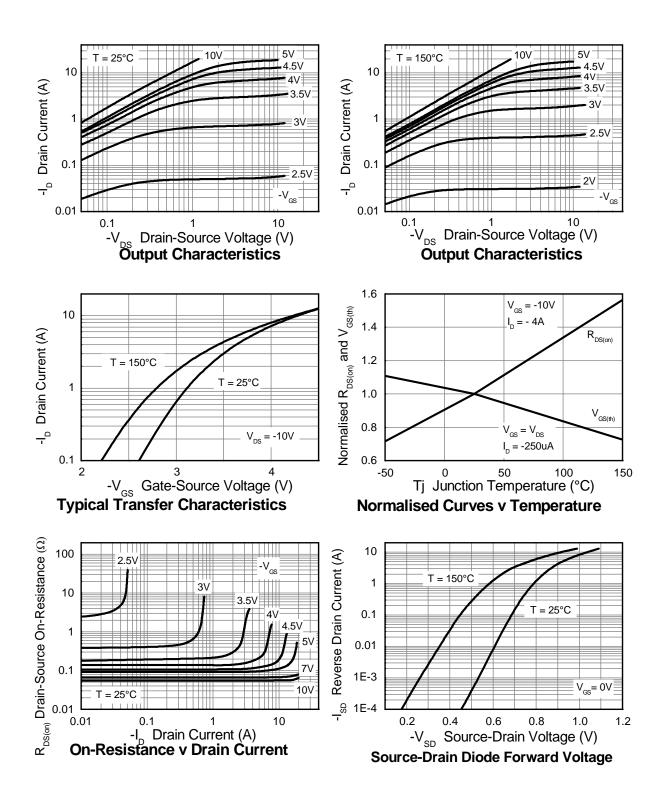
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test	Condition
OFF CHARACTERISTICS	Cymbol		176	max	Unit	1051	Contaition
Drain-Source Breakdown Voltage	BV _{DSS}	-40	_	_	V	I _D = -250μA, V ₀	35 = 0V
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-0.5	μA	$V_{DS} = -40V, V_{C}$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{I}$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	-1.0	_	-3.0	V	$I_D = -250 \mu A, V_I$	_{DS} = V _{GS}
Statia Drain Source On Desistance (Note 7)	D	_	_	0.080	Ω	$V_{GS} = -10V, I_{D}$	= -4A
Static Drain-Source On-Resistance (Note 7)	R _{DS(on)}	_	_	0.150	Ω	$V_{GS} = -4.5V, I_{D}$	= -2A
Forward Transconductance (Notes 7 & 8)	g fs	_	7.6	_	S	$V_{DS} = -15V, I_{D}$	= -4A
Diode Forward Voltage (Note 7)	V _{SD}	_	-0.86	-0.95	V	$I_{S} = -4A, V_{GS} = 0V$	
Reverse recovery time (Note 8)	t _{rr}	_	17.4	_	ns	I _S = -1.8A, di/dt = 100A/μs	
Reverse recovery charge (Note 8)	Q _{rr}	_	11.1	_	nC		
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	833	_		pF $V_{DS} = -20V, V_{GS} = 0V$ f = 1MHz	
Output Capacitance	C _{oss}	—	122	_	pF		
Reverse Transfer Capacitance	C _{rss}		78	_			
Total Gate Charge (Note 9)	Qg		7	_		V _{GS} = -4.5V	
Total Gate Charge (Note 9)	Qg	_	15.8	_			$V_{DS} = -20V$
Gate-Source Charge (Note 9)	Q _{gs}		3.6	—	nC	$V_{GS} = -10V \qquad I_D = -4A$	$I_D = -4A$
Gate-Drain Charge (Note 9)	Q _{gd}		2.7	_			
Turn-On Delay Time (Note 9)	t _{D(on)}		2.5	_			
Turn-On Rise Time (Note 9)	tr		3.3	—	ns $V_{DD} = -20V, V_{GS} = -10V$ $I_D = -1A, R_G \cong 6.0\Omega$		s = -10V
Turn-Off Delay Time (Note 9)	t _{D(off)}		47	—			6.0Ω
Turn-Off Fall Time (Note 9)	t _f	_	21	_			

 Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
For design aid only, not subject to production testing.
Switching characteristics are independent of operating junction temperatures. Notes:



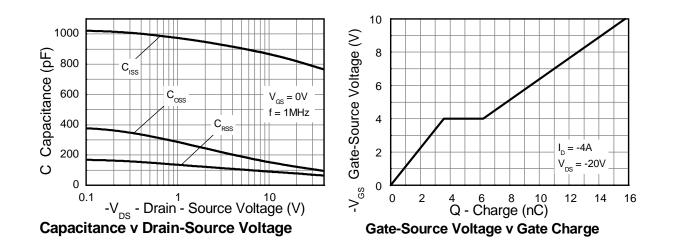
Typical Characteristics



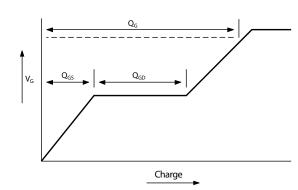
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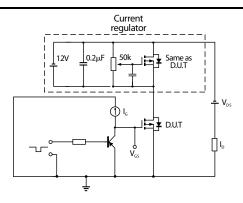
Typical Characteristics - continued



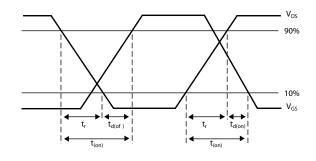
Test Circuits



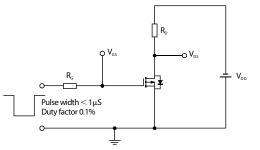
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms



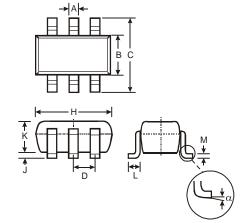
Switching time test circuit

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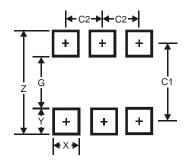


Package Outline Dimensions



	SOT-26					
Dim	Min	Max	Тур			
Α	0.35	0.50	0.38			
в	1.50	1.70	1.60			
с	2.70	3.00	2.80			
D			0.95			
Н	2.90	3.10	3.00			
ر	0.013	0.10	0.05			
K 1.00 1.30 1.10						
L	L 0.35 0.55 0.40					
М	0.10	0.20	0.15			
α	0°	8°	_			
All Dimensions in mm						

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95



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